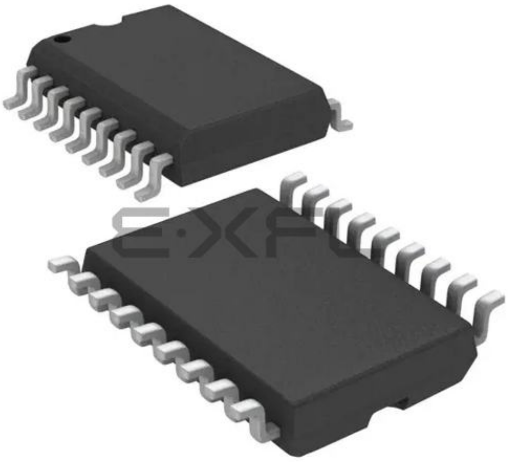

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f88t-i-so

TABLE 1-2: PIC16F87/88 PINOUT DESCRIPTION (CONTINUED)

Pin Name	PDIP/ SOIC Pin#	SSOP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
						PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT/CCP1[(5)]	6	7	7			
RB0				I/O	TTL	Bidirectional I/O pin.
INT				I	ST[(1)]	External interrupt pin.
CCP1				I/O	ST	Capture input, Compare output, PWM output.
RB1/SDI/SDA	7	8	8			
RB1				I/O	TTL	Bidirectional I/O pin.
SDI				I	ST	SPI data in.
SDA				I/O	ST	I^2C™ data.
RB2/SDO/RX/DT	8	9	9			
RB2				I/O	TTL	Bidirectional I/O pin.
SDO				O	ST	SPI data out.
RX				I		AUSART asynchronous receive.
DT				I/O		AUSART synchronous detect.
RB3/PGM/CCP1[(5)]	9	10	10			
RB3				I/O	TTL	Bidirectional I/O pin.
PGM				I/O	ST	Low-Voltage ICSP™ Programming enable pin.
CCP1				I	ST	Capture input, Compare output, PWM output.
RB4/SCK/SCL	10	11	12			
RB4				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
SCK				I/O	ST	Synchronous serial clock input/output for SPI.
SCL				I	ST	Synchronous serial clock Input for I^2C.
RB5/$\overline{SS}$/TX/CK	11	12	13			
RB5				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
$\overline{SS}$				I	TTL	Slave select for SPI in Slave mode.
TX				O		AUSART asynchronous transmit.
CK				I/O		AUSART synchronous clock.
RB6/AN5/PGC/T1OSO/ T1CKI	12	13	15			
RB6				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
AN5[(4)]				I		Analog input channel 5.
PGC				I/O	ST[(2)]	In-Circuit Debugger and programming clock pin.
T1OSO				O	ST	Timer1 oscillator output.
T1CKI				I	ST	Timer1 external clock input.
RB7/AN6/PGD/T1OSI	13	14	16			
RB7				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
AN6[(4)]				I		Analog input channel 6.
PGD				I	ST[(2)]	In-Circuit Debugger and ICSP programming data pin.
T1OSI				I	ST	Timer1 oscillator input.
VSS	5	5, 6	3, 5	P	–	Ground reference for logic and I/O pins.
VDD	14	15, 16	17, 19	P	–	Positive supply for logic and I/O pins.

Legend: I = Input O = Output I/O = Input/Output P = Power
– = Not used TTL = TTL Input ST = Schmitt Trigger Input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.
4: PIC16F88 devices only.
5: The CCP1 pin is determined by the CCPMX bit in Configuration Word 1 register.

2.2.2.6 PIE2 Register

The PIE2 register contains the individual enable bit for the EEPROM write operation interrupt.

REGISTER 2-6: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2 (ADDRESS 8Dh)

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0
OSFIE	CMIE	—	EEIE	—	—	—	—
bit 7							bit 0

bit 7 **OSFIE:** Oscillator Fail Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 6 **CMIE:** Comparator Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **EEIE:** EEPROM Write Operation Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 3-0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.6.3 CLOCK TRANSITION AND WDT

When clock switching is performed, the Watchdog Timer is disabled because the Watchdog ripple counter is used as the Oscillator Start-up Timer.

Note:	The OST is only used when switching to XT, HS and LP Oscillator modes.

Once the clock transition is complete (i.e., new oscillator selection switch has occurred), the Watchdog counter is re-enabled with the counter reset. This allows the user to synchronize the Watchdog Timer to the start of execution at the new clock frequency.

REGISTER 4-2: OSCCON: OSCILLATOR CONTROL REGISTER (ADDRESS 8Fh)

U-0	R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0
—	IRCF2	IRCF1	IRCF0	OSTS(1)	IOFS	SCS1	SCS0
bit 7							bit 0

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **IRCF<2:0>:** Internal RC Oscillator Frequency Select bits
000 = 31.25 kHz
001 = 125 kHz
010 = 250 kHz
011 = 500 kHz
100 = 1 MHz
101 = 2 MHz
110 = 4 MHz
111 = 8 MHz

bit 3 **OSTS:** Oscillator Start-up Time-out Status bit(1)
1 = Device is running from the primary system clock
0 = Device is running from T1OSC or INTRC as a secondary system clock

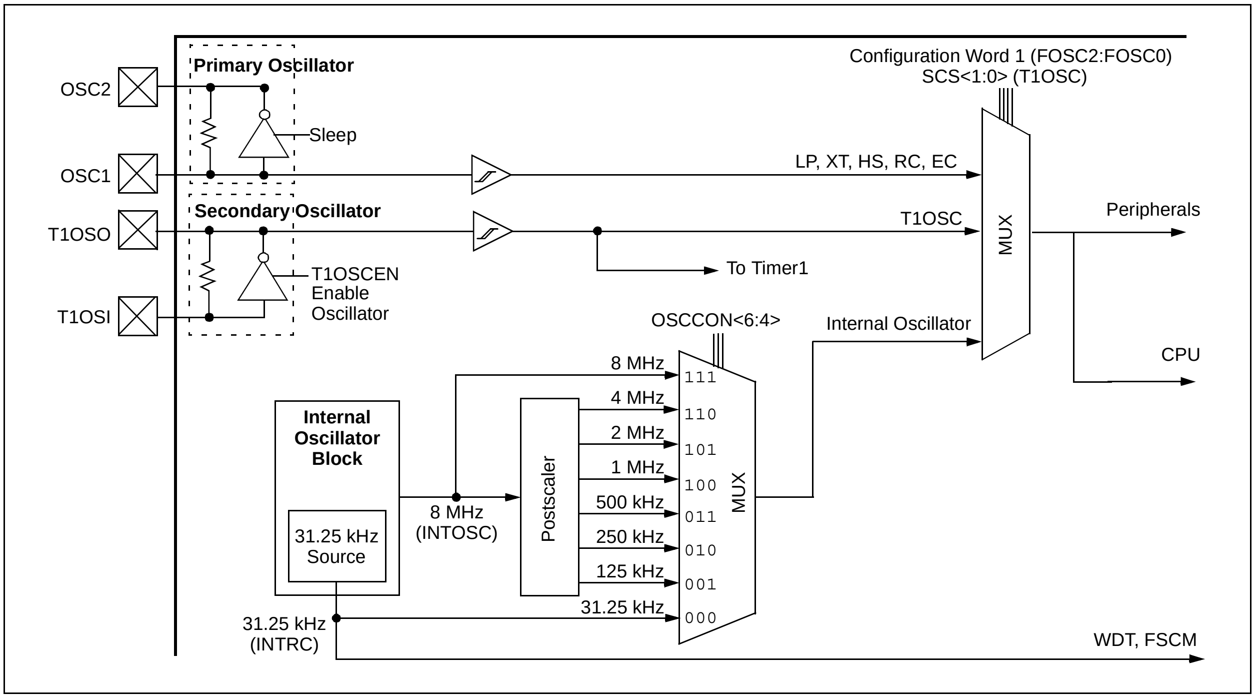
Note 1: Bit resets to ‘0’ with Two-Speed Start-up mode and LP, XT or HS selected as the oscillator mode.

bit 2 **IOFS:** INTOSC Frequency Stable bit
1 = Frequency is stable
0 = Frequency is not stable

bit 1-0 **SCS<1:0>:** Oscillator Mode Select bits
00 = Oscillator mode defined by FOSC<2:0>
01 = T1OSC is used for system clock
10 = Internal RC is used for system clock
11 = Reserved

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

FIGURE 4-6: PIC16F87/88 CLOCK DIAGRAM



4.6.4 MODIFYING THE IRCF BITS

The IRCF bits can be modified at any time regardless of which clock source is currently being used as the system clock. The internal oscillator allows users to change the frequency during run time. This is achieved by modifying the IRCF bits in the OSCCON register. The sequence of events that occur after the IRCF bits are modified is dependent upon the initial value of the IRCF bits before they are modified. If the INTRC (31.25 kHz, IRCF<2:0> = 000) is running and the IRCF bits are modified to any other value than '000', a 4 ms (approx.) clock switch delay is turned on. Code execution continues at a higher than expected frequency while the new frequency stabilizes. Time sensitive code should wait for the IOFS bit in the OSCCON register to become set before continuing. This bit can be monitored to ensure that the frequency is stable before using the system clock in time critical applications.

If the IRCF bits are modified while the internal oscillator is running at any other frequency than INTRC (31.25 kHz, IRCF<2:0> ≠ 000), there is no need for a 4 ms (approx.) clock switch delay. The new INTOSC frequency will be stable immediately after the **eight** falling edges. The IOFS bit will remain set after clock switching occurs.

Note:	Caution must be taken when modifying the IRCF bits using `BCF` or `BSF` instructions. It is possible to modify the IRCF bits to a frequency that may be out of the VDD specification range; for example, VDD = 2.0V and IRCF = 111 (8 MHz).

4.6.5 CLOCK TRANSITION SEQUENCE

Following are three different sequences for switching the internal RC oscillator frequency.

- Clock before switch: 31.25 kHz (IRCF<2:0> = 000)

1. IRCF bits are modified to an INTOSC/INTOSC postscaler frequency.
2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
3. The clock switching circuitry then waits for eight falling edges of requested clock, after which it switches CLKO to this new clock source.
4. The IOFS bit is clear to indicate that the clock is unstable and a 4 ms (approx.) delay is started. Time dependent code should wait for IOFS to become set.
5. Switchover is complete.

- Clock before switch: One of INTOSC/INTOSC postscaler (IRCF<2:0> ≠ 000)

1. IRCF bits are modified to INTRC (IRCF<2:0> = 000).
2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
3. The clock switching circuitry then waits for eight falling edges of requested clock, after which it switches CLKO to this new clock source.
4. Oscillator switchover is complete.

4.7 Power-Managed Modes

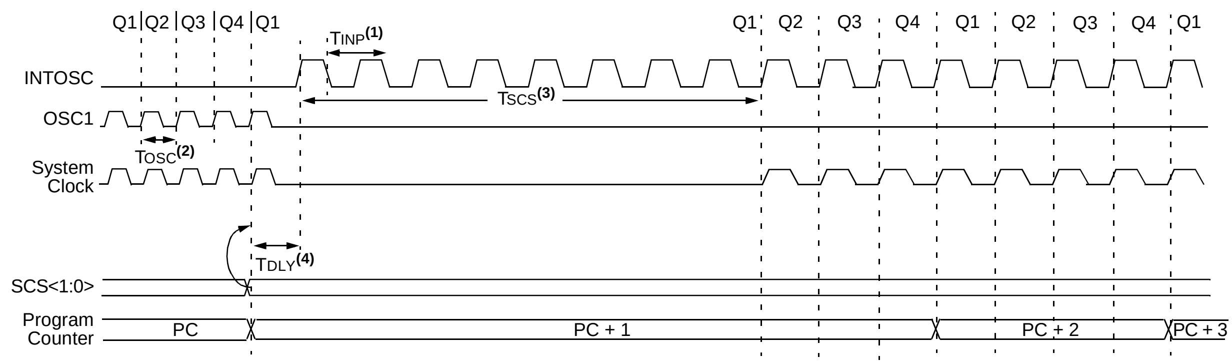
4.7.1 RC_RUN MODE

When SCS bits are configured to run from the INTRC, a clock transition is generated if the system clock is not already using the INTRC. The event will clear the OSTS bit, switch the system clock from the primary system clock (if SCS<1:0> = 00) determined by the value contained in the configuration bits, or from the T1OSC (if SCS<1:0> = 01) to the INTRC clock option and shut down the primary system clock to conserve power. Clock switching will not occur if the primary system clock is already configured as INTRC.

If the system clock does not come from the INTRC (31.25 kHz) when the SCS bits are changed and the IRCF bits in the OSCCON register are configured for a frequency other than INTRC, the frequency may not be stable immediately. The IOFS bit (OSCCON<2>) will be set when the INTOSC or postscaler frequency is stable, after 4 ms (approx.).

After a clock switch has been executed, the OSTS bit is cleared, indicating a low-power mode and the device does not run from the primary system clock. The internal Q clocks are held in the Q1 state until eight falling edge clocks are counted on the INTRC oscillator. After the eight clock periods have transpired, the clock input to the Q clocks is released and operation resumes (see Figure 4-7).

FIGURE 4-7: TIMING DIAGRAM FOR XT, HS, LP, EC AND EXTRC TO RC_RUN MODE



Note 1: T_{INP} = 32 μs typical.
2: T_{OSC} = 50 ns minimum.
3: T_{SCS} = 8 T_{INP}.
4: T_{DLY} = 1 T_{INP}.

7.2 Timer1 Operation in Timer Mode

Timer mode is selected by clearing the TMR1CS (T1CON<1>) bit. In this mode, the input clock to the timer is FOSC/4. The synchronize control bit, $\overline{\text{T1SYNC}}$ (T1CON<2>), has no effect since the internal clock is always in sync.

7.3 Timer1 Counter Operation

Timer1 may operate in Asynchronous or Synchronous mode, depending on the setting of the TMR1CS bit.

When Timer1 is being incremented via an external source, increments occur on a rising edge. After Timer1 is enabled in Counter mode, the module must first have a falling edge before the counter begins to increment.

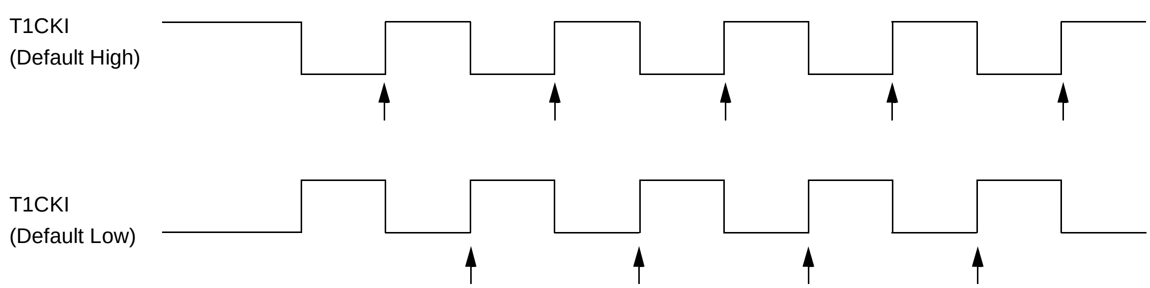
7.4 Timer1 Operation in Synchronized Counter Mode

Counter mode is selected by setting bit TMR1CS. In this mode, the timer increments on every rising edge of clock input on pin RB7/PGD/T1OSI when bit T1OSCEN is set, or on pin RB6/PGC/T1OSO/T1CKI when bit T1OSCEN is cleared.

If $\overline{\text{T1SYNC}}$ is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple counter.

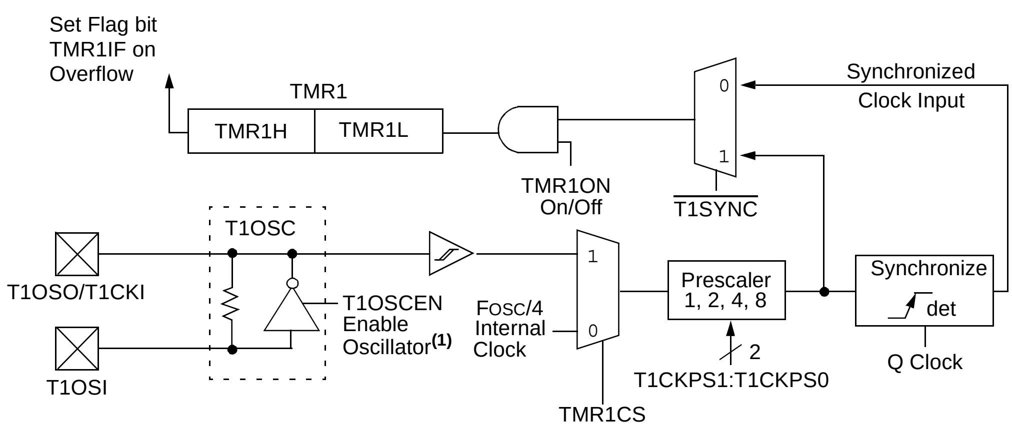
In this configuration, during Sleep mode, Timer1 will not increment even if the external clock is present since the synchronization circuit is shut off. The prescaler, however, will continue to increment.

FIGURE 7-1: TIMER1 INCREMENTING EDGE



Note: Arrows indicate counter increments.

FIGURE 7-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter is turned off. This eliminates power drain.

REGISTER 10-2: SSPCON: SYNCHRONOUS SERIAL PORT CONTROL REGISTER (ADDRESS 14h)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN(1)	CKP	SSPM3	SSPM2	SSPM1	SSPM0
bit 7							bit 0

bit 7 **WCOL:** Write Collision Detect bit

1 = An attempt to write the SSPBUF register failed because the SSP module is busy (must be cleared in software)
0 = No collision

bit 6 **SSPOV:** Receive Overflow Indicator bit

<u>In SPI mode:</u>
1 = A new byte is received while the SSPBUF register is still holding the previous data. In case of overflow, the data in SSPSR is lost. Overflow can only occur in Slave mode. The user must read the SSPBUF, even if only transmitting data, to avoid setting overflow. In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPBUF register.
0 = No overflow

<u>In I^{2}C mode:</u>
1 = A byte is received while the SSPBUF register is still holding the previous byte. SSPOV is a “don’t care” in Transmit mode. SSPOV must be cleared in software in either mode.
0 = No overflow

bit 5 **SSPEN:** Synchronous Serial Port Enable bit(1)

<u>In SPI mode:</u>
1 = Enables serial port and configures SCK, SDO and SDI as serial port pins
0 = Disables serial port and configures these pins as I/O port pins

<u>In I^{2}C mode:</u>
1 = Enables the serial port and configures the SDA and SCL pins as serial port pins
0 = Disables serial port and configures these pins as I/O port pins

Note 1: In both modes, when enabled, these pins must be properly configured as input or output.

bit 4 **CKP:** Clock Polarity Select bit

<u>In SPI mode:</u>
1 = Transmit happens on falling edge, receive on rising edge. Idle state for clock is a high level.
0 = Transmit happens on rising edge, receive on falling edge. Idle state for clock is a low level.

<u>In I^{2}C Slave mode:</u>
SCK release control
1 = Enable clock
0 = Holds clock low (clock stretch). (Used to ensure data setup time.)

bit 3-0 **SSPM<3:0>:** Synchronous Serial Port Mode Select bits

0000 = SPI Master mode, clock = OSC/4
0001 = SPI Master mode, clock = OSC/16
0010 = SPI Master mode, clock = OSC/64
0011 = SPI Master mode, clock = TMR2 output/2
0100 = SPI Slave mode, clock = SCK pin. $\overline{SS}$ pin control enabled.
0101 = SPI Slave mode, clock = SCK pin. $\overline{SS}$ pin control disabled. $\overline{SS}$ can be used as I/O pin.
0110 = I^{2}C Slave mode, 7-bit address
0111 = I^{2}C Slave mode, 10-bit address
1011 = I^{2}C Firmware Controlled Master mode (Slave Idle)
1110 = I^{2}C Slave mode, 7-bit address with Start and Stop bit interrupts enabled
1111 = I^{2}C Slave mode, 10-bit address with Start and Stop bit interrupts enabled
1000, 1001, 1010, 1100, 1101 = Reserved

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

When setting up an asynchronous transmission, follow these steps:

1. Initialize the SPBRG register for the appropriate baud rate. If a high-speed baud rate is desired, set bit BRGH (**Section 11.1 "AUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set transmit bit TX9.
5. Enable the transmission by setting bit TXEN which will also set bit TXIF.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Load data to the TXREG register (starts transmission).
8. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

FIGURE 11-2: ASYNCHRONOUS MASTER TRANSMISSION

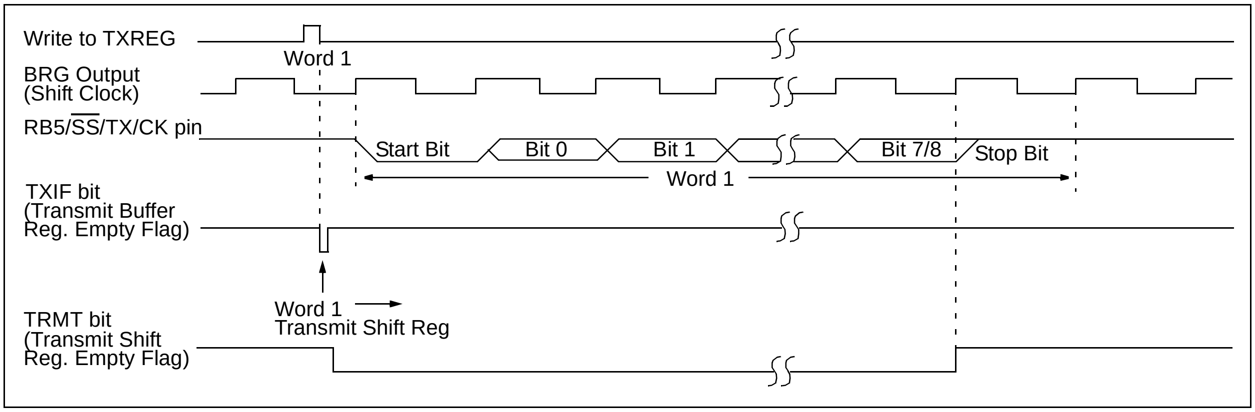
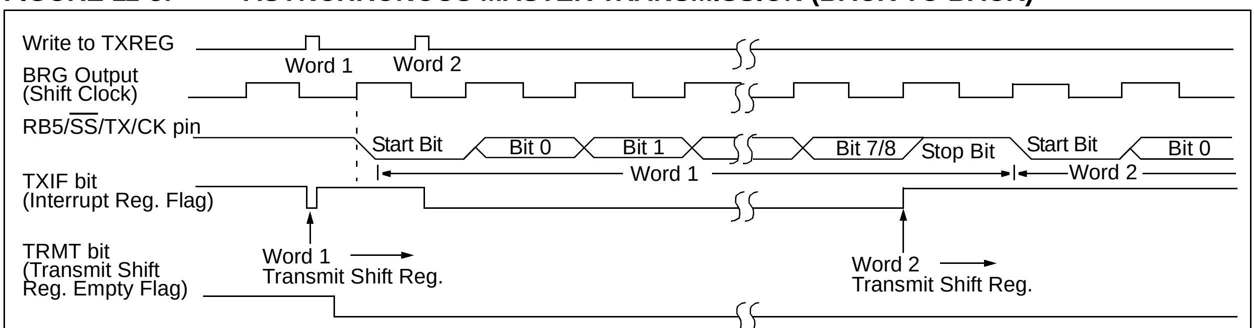


FIGURE 11-3: ASYNCHRONOUS MASTER TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 11-7: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF(1)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19h	TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
8Ch	PIE1	—	ADIE(1)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for asynchronous transmission.
Note 1: This bit is only implemented on the PIC16F88. The bit will read '0' on the PIC16F87.

13.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with I/O port pins RA0 through RA3, while the outputs are multiplexed to pins RA3 and RA4. The on-chip Voltage Reference (**Section 14.0 "Comparator Voltage Reference Module"**) can also be an input to the comparators.

The CMCON register (Register 13-1) controls the comparator input and output multiplexors. A block diagram of the various comparator configurations is shown in Figure 13-1.

REGISTER 13-1: CMCON: COMPARATOR MODULE CONTROL REGISTER (ADDRESS 9Ch)

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT:** Comparator 2 Output bit
When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-
When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT:** Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV:** Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV:** Comparator 1 Output Inversion bit
1 = C1 output inverted
0 = C1 output not inverted

bit 3 **CIS:** Comparator Input Switch bit
When CM2:CM0 = 001:
1 = C1 VIN- connects to RA3
0 = C1 VIN- connects to RA0
When CM2:CM0 = 010:
1 = C1 VIN- connects to RA3
C2 VIN- connects to RA2
0 = C1 VIN- connects to RA0
C2 VIN- connects to RA1

bit 2-0 **CM<2:0>:** Comparator Mode bits

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

13.7 Comparator Operation During Sleep

When a comparator is active and the device is placed in Sleep mode, the comparator remains active and the interrupt is functional, if enabled. This interrupt will wake-up the device from Sleep mode when enabled. While the comparator is powered up, higher Sleep currents than shown in the power-down current specification will occur. Each operational comparator will consume additional current, as shown in the comparator specifications. To minimize power consumption while in Sleep mode, turn off the comparators, CM<2:0> = `111`, before entering Sleep. If the device wakes up from Sleep, the contents of the CMCON register are not affected.

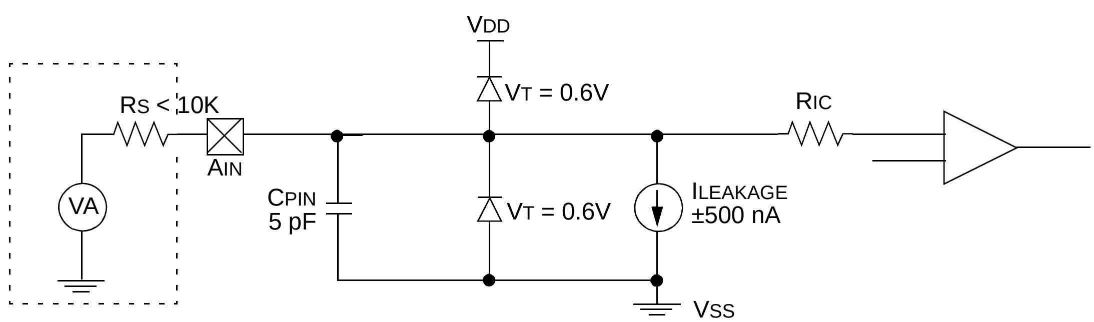
13.8 Effects of a Reset

A device Reset forces the CMCON register to its Reset state, causing the comparator module to be in the Comparator Off mode, CM<2:0> = `111`.

13.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 13-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to V_{DD} and V_{SS}. The analog input, therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up condition may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 13-4: ANALOG INPUT MODEL



Legend:

C_{PIN}	=	Input Capacitance
V_T	=	Threshold Voltage
$I_{LEAKAGE}$	=	Leakage Current at the pin due to various junctions
R_{IC}	=	Interconnect Resistance
R_S	=	Source Impedance
VA	=	Analog Voltage

15.2 Reset

The PIC16F87/88 differentiates between various kinds of Reset:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ Reset during normal operation
- $\overline{\text{MCLR}}$ Reset during Sleep
- WDT Reset during normal operation
- WDT wake-up during Sleep
- Brown-out Reset (BOR)

Some registers are not affected in any Reset condition. Their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on Power-on Reset (POR), on the $\overline{\text{MCLR}}$ and WDT Reset, on $\overline{\text{MCLR}}$ Reset during Sleep and Brown-out Reset (BOR). They are not affected by a WDT wake-up which is viewed as the resumption of normal operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different Reset situations, as indicated in Table 15-3. These bits are used in software to determine the nature of the Reset. Upon a POR, BOR or wake-up from Sleep, the CPU requires approximately 5-10 μs to become ready for code execution. This delay runs in parallel with any other timers. See Table 15-4 for a full description of Reset states of all registers.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 15-1.

FIGURE 15-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

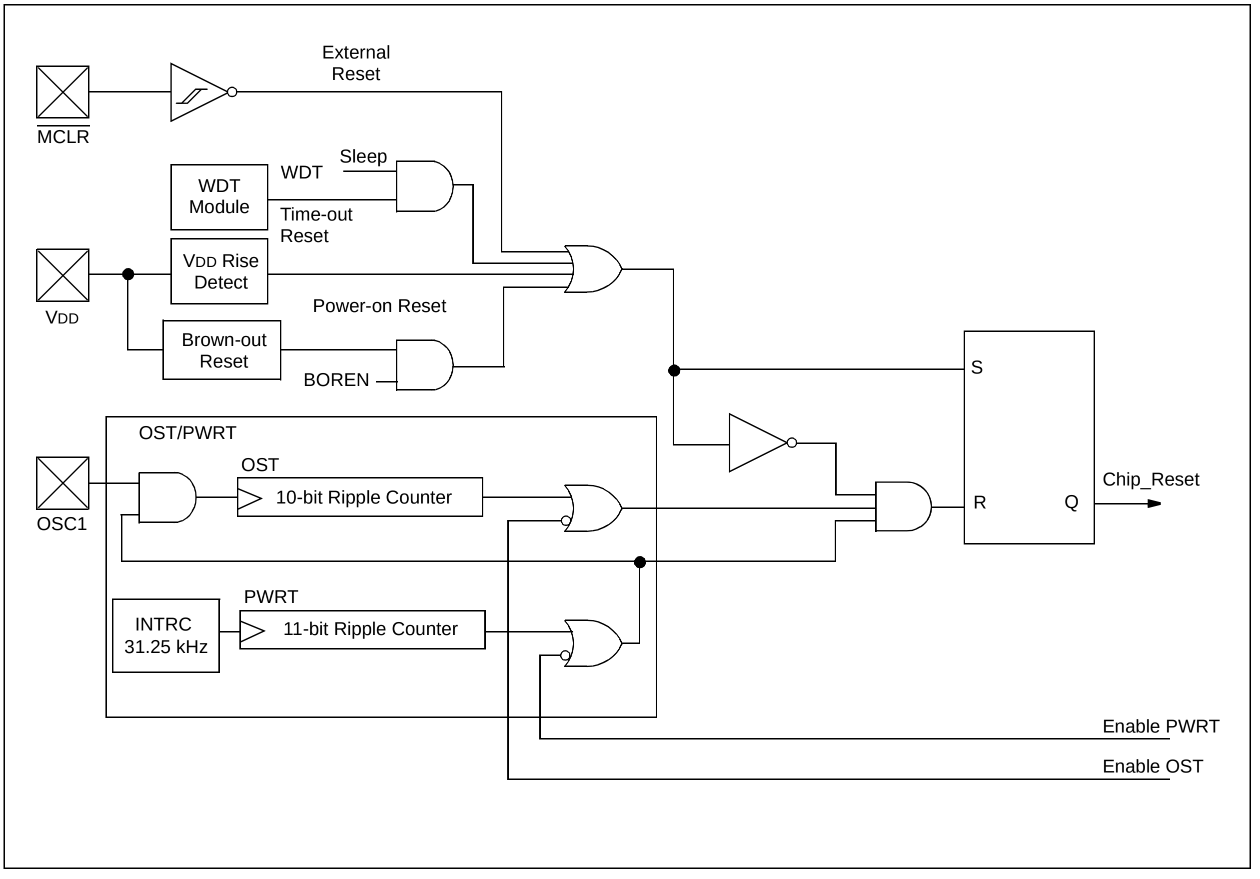


FIGURE 15-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO VDD THROUGH PULL-UP RESISTOR)

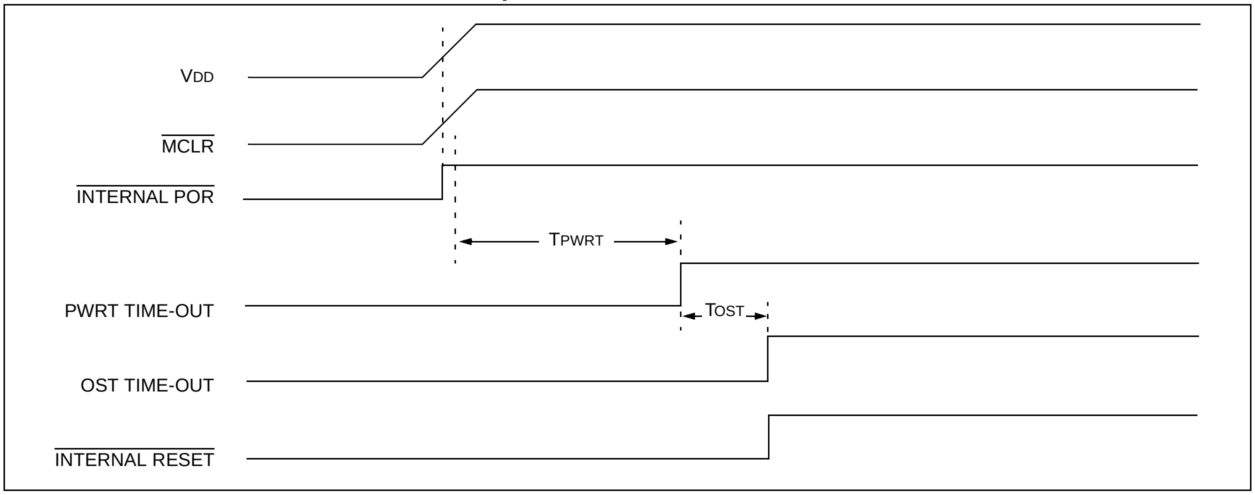


FIGURE 15-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO VDD THROUGH RC NETWORK): CASE 1

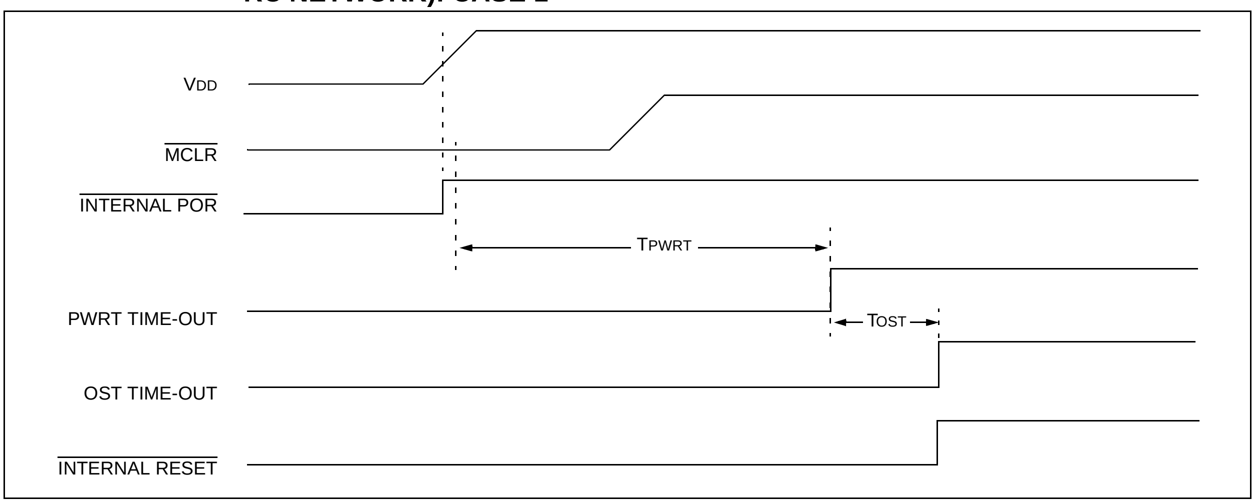
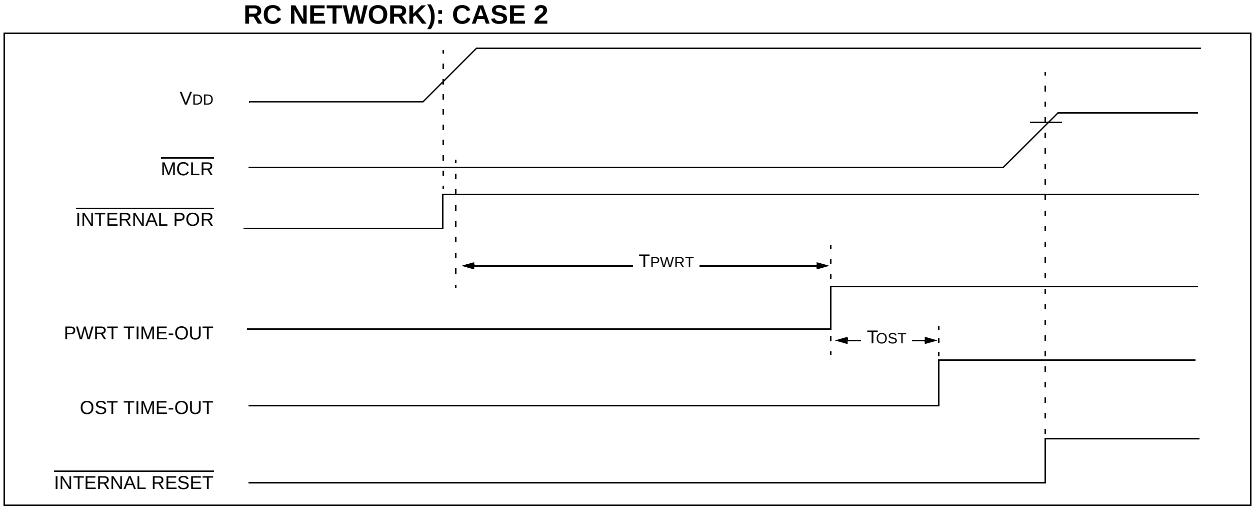


FIGURE 15-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO VDD THROUGH RC NETWORK): CASE 2



SUBLW — Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: $0 \leq k \leq 255$

Operation: k – (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (two's complement method) from the eight-bit literal 'k'. The result is placed in the W register.

SUBWF — Subtract W from f

Syntax: [*label*] SUBWF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

Operation: (f) – (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (two's complement method) W register from register 'f'. If 'd' = `0`, the result is stored in the W register. If 'd' = `1`, the result is stored back in register 'f'.

SWAPF — Swap Nibbles in f

Syntax: [*label*] SWAPF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

Operation: (f<3:0>) → (destination<7:4>),
(f<7:4>) → (destination<3:0>)

Status Affected: None

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' = `0`, the result is placed in W register. If 'd' = `1`, the result is placed in register 'f'.

XORLW — Exclusive OR Literal with W

Syntax: [*label*] XORLW k

Operands: $0 \leq k \leq 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Description: The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF — Exclusive OR W with f

Syntax: [*label*] XORWF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (destination)

Status Affected: Z

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' = `0`, the result is stored in the W register. If 'd' = `1`, the result is stored back in register 'f'.

18.2 DC Characteristics: Power-Down and Supply Current PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

PIC16LF87/88 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for industrial					
PIC16F87/88 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**	
	Supply Current (I_{DD})(2,3)					
	All devices	1.8	2.3	mA	-40°C	V_{DD} = 4.0V; F_{OSC} = 20 MHz (HS Oscillator)
		1.6	2.2	mA	+25°C	
		1.3	2.2	mA	+85°C	
	All devices	3.0	4.2	mA	-40°C	V_{DD} = 5.0V
		2.5	4.0	mA	+25°C	
		2.5	4.0	mA	+85°C	
	Extended devices	3.0	5.0	mA	+85°C	

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD};
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be estimated by the formula Ir = $V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

18.2 DC Characteristics: Power-Down and Supply Current PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

PIC16LF87/88 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F87/88 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2,3)						
	PIC16LF87/88	8	20	μA	-40°C	VDD = 2.0V	FOSC = 31.25 kHz (**RC_RUN** mode, Internal RC Oscillator)
		7	15	μA	+25°C		
		7	15	μA	+85°C		
	PIC16LF87/88	16	30	μA	-40°C	VDD = 3.0V	
		14	25	μA	+25°C		
		14	25	μA	+85°C		
	All devices	32	40	μA	-40°C	VDD = 5.0V	
		29	35	μA	+25°C		
		29	35	μA	+85°C		
	Extended devices	35	45	μA	+125°C		
	PIC16LF87/88	132	160	μA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, Internal RC Oscillator)
		126	155	μA	+25°C		
		126	155	μA	+85°C		
	PIC16LF87/88	260	310	μA	-40°C	VDD = 3.0V	
		230	300	μA	+25°C		
		230	300	μA	+85°C		
	All devices	560	690	μA	-40°C	VDD = 5.0V	
		500	650	μA	+25°C		
		500	650	μA	+85°C		
	Extended devices	570	710	μA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

18.4 DC Characteristics: PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in DC Specification, **Section 18.1 "DC Characteristics: Supply Voltage"**.				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +125°C
D083		OSC2/CLKO (RC oscillator configuration)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +125°C
	VOH	**Output High Voltage**					
D090		I/O ports **(Note 3)**	VDD – 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +125°C
D092		OSC2/CLKO (RC oscillator configuration)	VDD – 0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +125°C
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (in RC mode)	—	—	50	pF	
D102	CB	SCL, SDA in I²C™ mode	—	—	400	pF	
		Data EEPROM Memory					
D120	ED	Endurance	100K 10K	1M 100K	— —	E/W E/W	-40°C to 85°C +85°C to +125°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write, VMIN = min. operating voltage
D122	TDEW	Erase/Write Cycle Time	—	4	8	ms	
		Program Flash Memory					
D130	EP	Endurance	10K 1K	100K 10K	— —	E/W E/W	-40°C to 85°C +85°C to +125°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	
D132A		VDD for Erase/Write	VMIN	—	5.5	V	Using EECON to read/write, VMIN = min. operating voltage
D133	TPE	Erase Cycle Time	—	2	4	ms	
D134	TPW	Write Cycle Time	—	2	4	ms	

* These parameters are characterized but not tested.

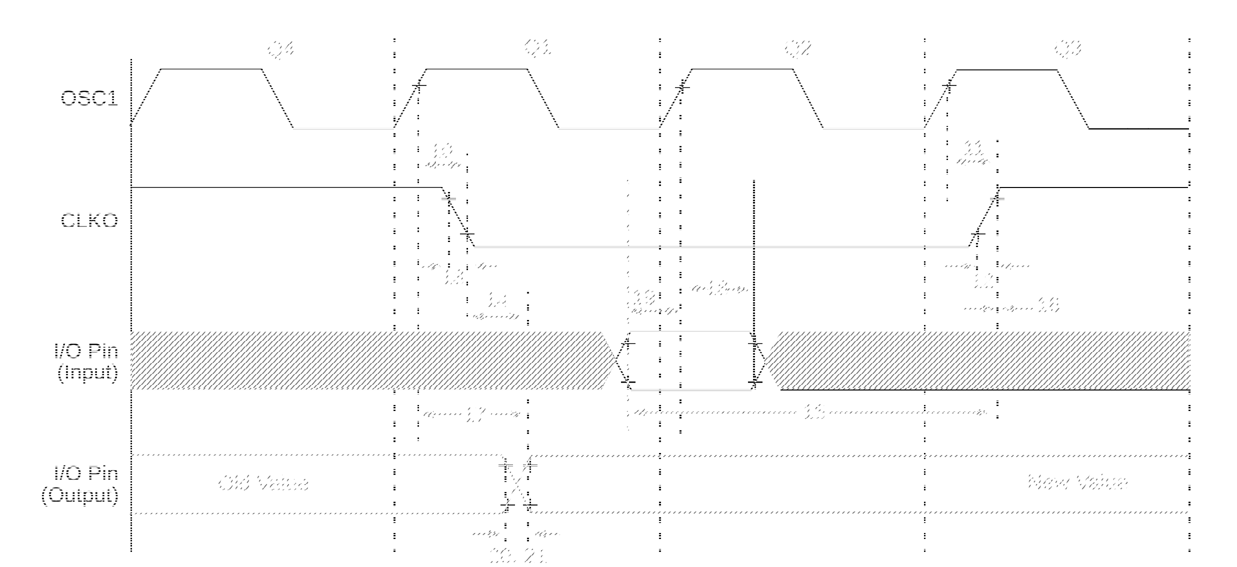
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC16F87/88 be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 18-5: CLKO AND I/O TIMING



Note: Refer to Figure 18-3 for load conditions.

TABLE 18-4: CLKO AND I/O TIMING REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1 ↑ to CLKO ↓		—	75	200	ns	**(Note 1)**
11*	TosH2ckH	OSC1 ↑ to CLKO ↑		—	75	200	ns	**(Note 1)**
12*	TckR	CLKO Rise Time		—	35	100	ns	**(Note 1)**
13*	TckF	CLKO Fall Time		—	35	100	ns	**(Note 1)**
14*	TckL2ioV	CLKO ↓ to Port Out Valid		—	—	0.5 TCY + 20	ns	**(Note 1)**
15*	TioV2ckH	Port In Valid before CLKO ↑		TOSC + 200	—	—	ns	**(Note 1)**
16*	TckH2ioI	Port In Hold after CLKO ↑		0	—	—	ns	**(Note 1)**
17*	TosH2ioV	OSC1 ↑ (Q1 cycle) to Port Out Valid		—	100	255	ns	
18*	TosH2ioI	OSC1 ↑ (Q2 cycle) to Port Input Invalid (I/O in hold time)	PIC16**F**87/88	100	—	—	ns	
			PIC16**LF**87/88	200	—	—	ns	
19*	TioV2osH	Port Input Valid to OSC1 ↑ (I/O in setup time)		0	—	—	ns	
20*	TIOR	Port Output Rise Time	PIC16**F**87/88	—	10	40	ns	
			PIC16**LF**87/88	—	—	145	ns	
21*	TIOF	Port Output Fall Time	PIC16**F**87/88	—	10	40	ns	
			PIC16**LF**87/88	—	—	145	ns	
22††*	TINP	INT Pin High or Low Time		TCY	—	—	ns	
23††*	TRBP	RB7:RB4 Change INT High or Low Time		TCY	—	—	ns	

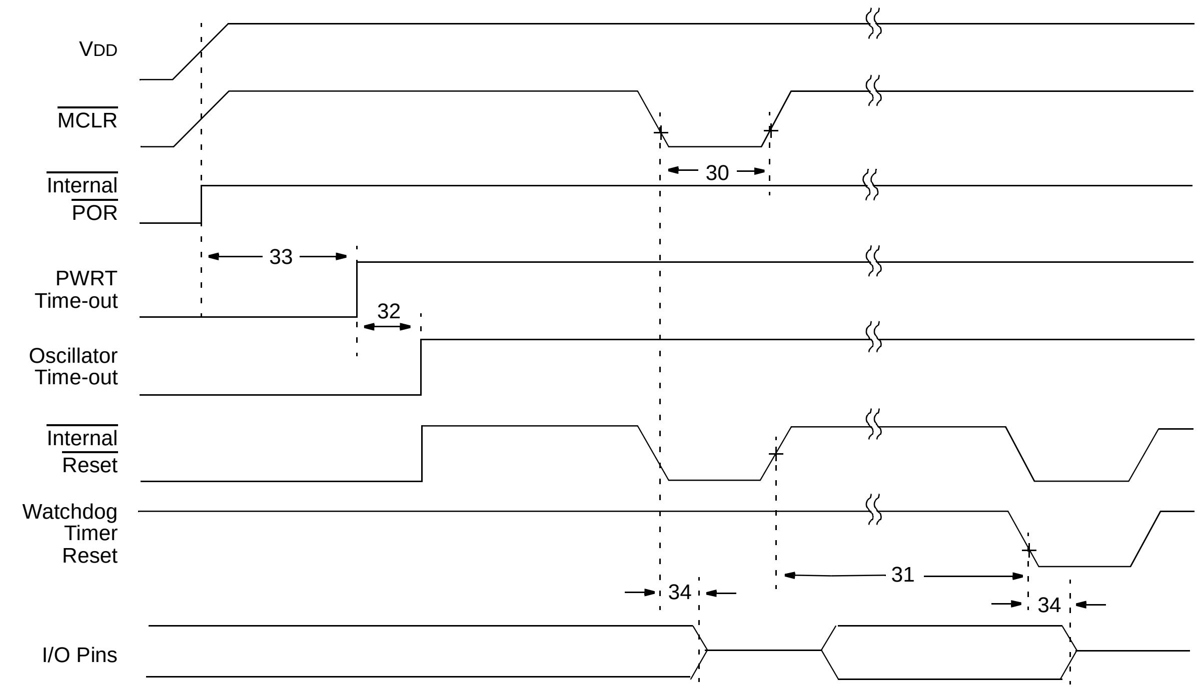
* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC mode where CLKO output is 4 x TOSC.

FIGURE 18-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 18-3 for load conditions.

FIGURE 18-7: BROWN-OUT RESET TIMING

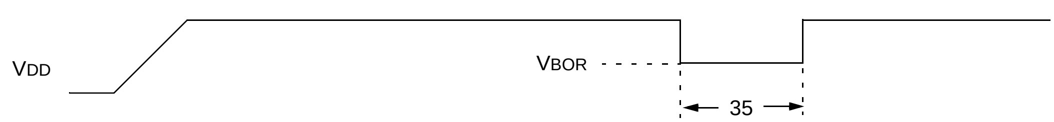


TABLE 18-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (Low)	2	—	—	μs	VDD = 5V, -40°C to +85°C
31*	TWDT	Watchdog Timer Time-out Period (16-bit prescaler = 0100 and no postscaler)	13.6	16	18.4	ms	VDD = 5V, -40°C to +85°C
32	TOST	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	TPWRT	Power-up Timer Period	61.2	72	82.8	ms	VDD = 5V, -40°C to +85°C
34	TIOZ	I/O High-impedance from MCLR Low or Watchdog Timer Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—	—	μs	VDD ≤ VBOR (D005)

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC16F87: Standard VDD range PIC16F87T: (Tape and Reel) PIC16LF87: Extended VDD range
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	P = PDIP SO = SOIC SS = SSOP ML = QFN
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.

Examples:

a) PIC16F87-I/P = Industrial temp., PDIP package, Extended VDD limits.

b) PIC16F87-I/SO = Industrial temp., SOIC package, normal VDD limits.

Note 1: F = CMOS Flash
LF = Low-power CMOS Flash
2: T = in tape and reel – SOIC, SSOP packages only.